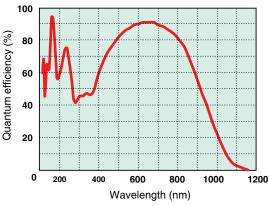
BT-CCD camera C8000-30



The C8000-30 employs an ultrahigh-sensitivity back-thinned CCD sensor made by Hamamatsu, which offers extremely high quantum efficiency in a wide range of UV, VIS and NIR wavelengths. The high UV sensitivity from 120 nm is useful for semiconductor mask inspection and measurement applications. Also, the high NIR sensitivity is useful for fluorescence measurement, NIR LD measurement and so on.

SPECTRAL RESPONSE



* Without sapphire window. With the sapphire window, the spectral response is decreased due to the transmittance characteristics of the window.

FEATURES

- High-sensitivity imaging from UV to nearinfrared wavelengths
 - UV: Quantum efficiency over 60 % (at 200 nm)
 - Near-infrared: Quantum efficiency over 90 % (at 650 nm)
- Quantum efficiency in UV source (reference data)

(**************************************						
Fourth harmonic generation of a YAG laser	i line					
266	365					

(This is typical value)

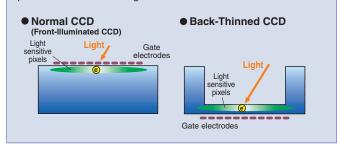
Light source	F ₂	ArF	KrF	Fourth harmonic generation of a YAG laser	i line
Wavelength (nm)	157	193	248	266	365
Quantum efficiency (%) (typ.)	84	57	69	50	47

- * UV light irradiation may cause a drop in sensitivity and increase the dark current of the CCD sensor.
- Real time background subtraction
- Recursive filter (2, 4, 8, 16, 32 and 64 frames selectable)

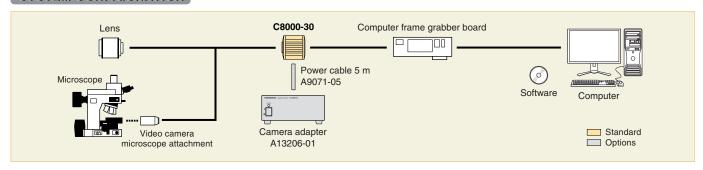
PRINCIPLE

In a normal CCD with front-illuminated CCD structure, the light sensitive pixels have a charge transfer function as well, and this function requires the front surface of light sensitive pixels to be covered by a semi-transparent Poly-Si electrode for the charge transfer function. The Poly-Si electrode absorbs some percentage of incoming photons depending on their wavelength. Especially of of the UV light is not able to reach the light sensitive pixels.

To overcome this disadvantage, in a back-thinned CCD, the CCD is turned upside down and this back side of the CCD is thinned to 10-15 μm in thickness. Incident photons now enter the CCD from the back-thinned side, without the Poly-Si electrode in the light path. Then QE values of greater than 90 % can be achieved.



SYSTEM CONFIGURATION



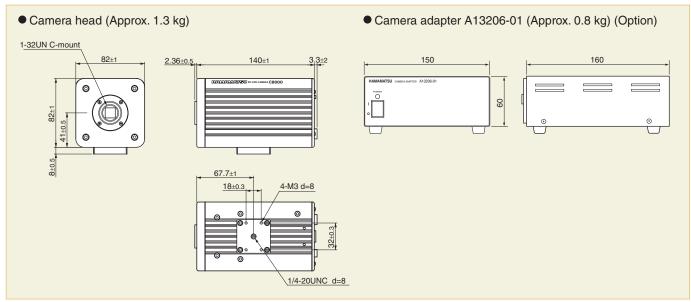
SYSTEM SPECIFICATIONS

Type number			C8000-30			
Imaging device			Back-thinned frame transfer CCD			
Effective number of pixels			640 (H) × 480 (V)			
Cell size			14 μm (H) × 14 μm (V)			
Effective area			8.96 mm (H) × 6.72 mm (V)			
	1×1		31.4 frames/s			
Frame rate	binning	2×2	58.3 frames/s			
		4×4	101.8 frames/s			
Readout noise (rms) (typ.)			150 electrons			
Full well capacity (typ.)			30 000 electrons			
Cooling method			Passive air-cooled			
Cooling temperature			+ 5 °C (room temperature + 20 °C)			
A/D converter			12 bit			
Exposure time			30.8 ms to 1 s			
Analog gain			Approx. 1 to 5 times (16 steps)			
Sub-array			8 pixels increments (V)			
External trigger mode			Edge trigger, Level trigger, Start trigger, Synchronous readout trigger			
Image processing functions			Background subtraction, Recursive filter			
Lens mount			C-mount			
Interface			CameraLink Base Configuration			
External cont	trol		CameraLink			
Power requir	ements		DC +12 V			
Power consumption			Approx. 10 VA			
Ambient operating temperature			0 °C to + 40 °C			
Performance guaranteed temperature			0 °C to + 30 °C			
Ambient storage temperature			- 10 °C to + 50 °C			
Ambient operating humidity			70 % max. (with no condensation)			
Ambient storage humidity			90 % max. (with no condensation)			

OPTIONS

Camera adapter : A13206-01Power cable 5 m : A9071-05

DIMENSIONAL OUTLINES (Unit: mm)



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